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REVISION HISTORY						
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	DATABASE FILE NAME	GERBER FILE NAME	INCORPORATOR
00	C01458	INITIAL RELEASE	DARNO	N/A	N/A	DARNO
01	A41532	INCORPORATED PER DCN # A41532	DPARK	N/A	N/A	DPARK
02	C17579	UPDATE TO MS-034 SPECIFICATIONS CAP TOLERANCE WAS 11.50 +0.70/-0.05	THUFF	N/A	N/A	EHUDS

F

E

D

C

B

A

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- REFERENCE SPECIFICATIONS:
- A. AWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
 - B. AWW SPEC #001-0519-2062: MARKING.
 - C. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MS-034/A VARIATION AAD-1



A1 BALL PAD CORNER I.D. FOR PLATE MOLD: TO BE MARKED BY INK.
AUTO MOLD: DIMPLE TO BE FORMED BY MOLD CAP.



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY
THE SPHERICAL CROWNS OF THE SOLDER BALLS.



DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER,
PARALLEL TO PRIMARY DATUM C.

4.

THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 144.

3.

THE MAXIMUM SOLDER BALL MATRIX SIZE IS 12 X 12.

2.

THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.

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ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		THIRD ANGLE PROJECTION		Anchor Technology, Inc. Chandler, Arizona, USA Anam Semiconductor, Inc., Seoul, Korea Anchor Technology Philippines, Inc. Manila, Philippines		
DECIMAL X.X ±0.1	ANGULAR ±1°	APPROVALS	DATE			
X.XX ±0.05		DESIGNED R. FUENTES	09/18/96			
X.XXX ±0.030		CHECKED D. ARNOLD	09/18/96			
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994		PRODUCT MANAGER B. GOGUE	09/18/96			
MATERIAL N/A		RELEASED YM KANG	04/15/97	TITLE PACKAGE OUTLINE - PBGA CUSTOM, 12 X 12 MATRIX, 13.00mm X 13.00mm, 11.50mm X 11.50mm X 0.80mm MOLD CAP, 1.00mm PITCH, LAMINATE SUBSTRATE, AWW	SIZE A3	SD NUMBER
FINISH N/A				STRIP DWG NUMBER/REV N/A	PKG OUTLINE DWG NO. N/A	DWG NUMBER 71787
DO NOT SCALE DRAWING				SCALE NONE	SHEET 1 OF 3	REV 02

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